IPIC (Intelligent Power IC) High Side Solenoid Driver

HITACHI

ADE-207-207 (Z) 1st Edition July 1996

Description

The HA13705C is high side power driver IC with protectors and diagnostic function. The device is especially designed to switch inductive loads.

Functions

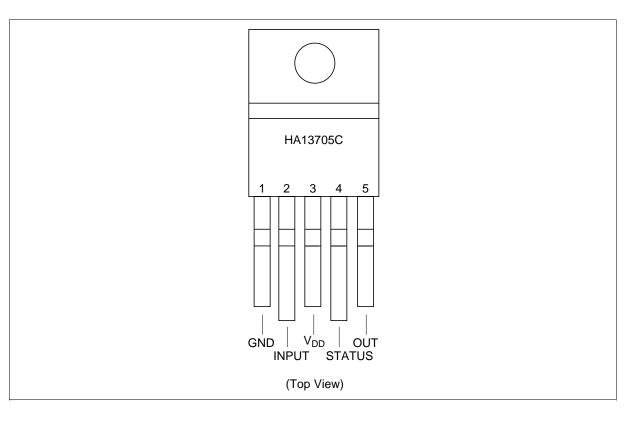
- Power MOS source follower output (2 A)
- With Over Voltage Shut Down circuit (OVSD)
- With Over Current protector circuit (OCSD)
- With Over Temperature Shut Down circuit (OTSD)
- With diagnostic circuit and status output
- With fail safe function under input open circuit condition
- With low voltage inhibit circuit (LVI)
- With output negative voltage clamp circuit

Features

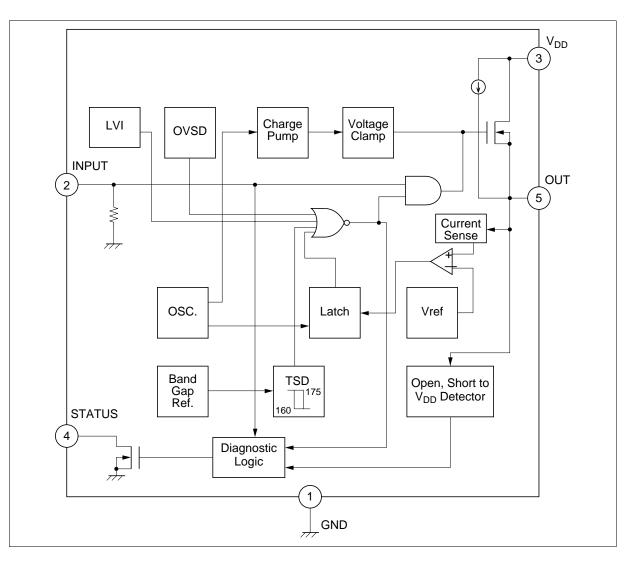
- Protected against 60 V load dump condition
- Low R_{ON} (0.17 Ω Typ)
- Wide operating supply voltage range ($V_{DD} = 7 \text{ V to } 25 \text{ V}$)
- High sustaining voltage (-25 V)
- Protected against reverse supply voltage (-13 V)
- Protected against short circuit condition
- Input compatible with TTL, LS-TTL, or 5 V CMOS



Pin Arrangement



Block Diagram



Truth Table

Mode	In	Out	Status	
Normal	L	L	L	
	Н	Н	Н	
Load short	L	L	L	
	Н	L	L	
Load open	L	Н	Н	
	Н	Н	Н	
Short to V _{DD}	L	Н	Н	
	Н	Н	Н	
OTSD *1	L	L	L	
	Н	L	L	
OVSD *2	L	L	Н	
	Н	L	Н	
LVI *3	L	L	Н	
	Н	L	Н	

L: Low level (0.8 V)

H: High level (2.0 V)

Notes: 1. OTSD: Over temperature shut down

2. OVSD: Over voltage shut down

3. LVI: Low voltage inhhibit

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Rating	Unit	Notes
Continuous supply voltage	V _{DD}	-13 to 35	V	1
Transient supply voltage	V _{DD}	60	V	2
Input voltage	V _{IN}	-0.3 to 30	V	
Output voltage	Vout	–25 to V_{DD}	V	3
Status voltage	Vs	–0.3 to +15	V	
Output current	lout	—	А	3, 4
Status current	ls	5	mA	
Power dissipation	P _T	—	W	5
Package thermal resistance/ Junction to case	өј–с	5	°C/W	
Package thermal resistance/ Junction to air	θј–а	70	°C/W	
Junction temperature range	Tj	-40 to 150	°C	
Storage temperature range	Tstg	-55 to +150	°C	

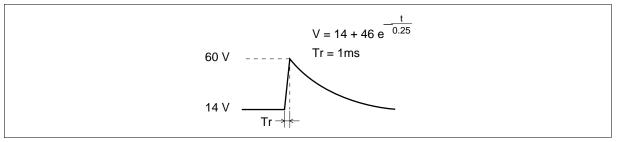
Notes: 1. Recommended operating voltage:

 V_{DD} = 7 to 16 V (Normal)

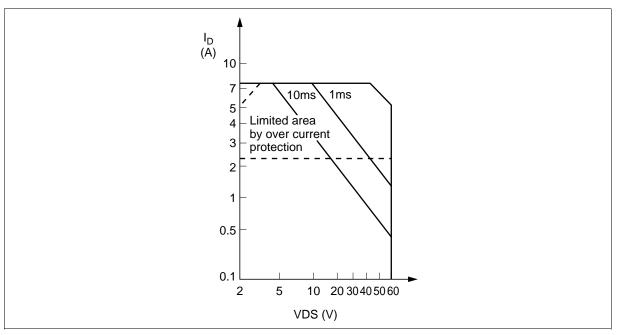
16 to 25 V (Jump up start 5 minutes MAX)

-13 V (Reverse Battely 5 minutes MAX)

2. Load dump condition



3. Output Transistor ASO (Reference Data)

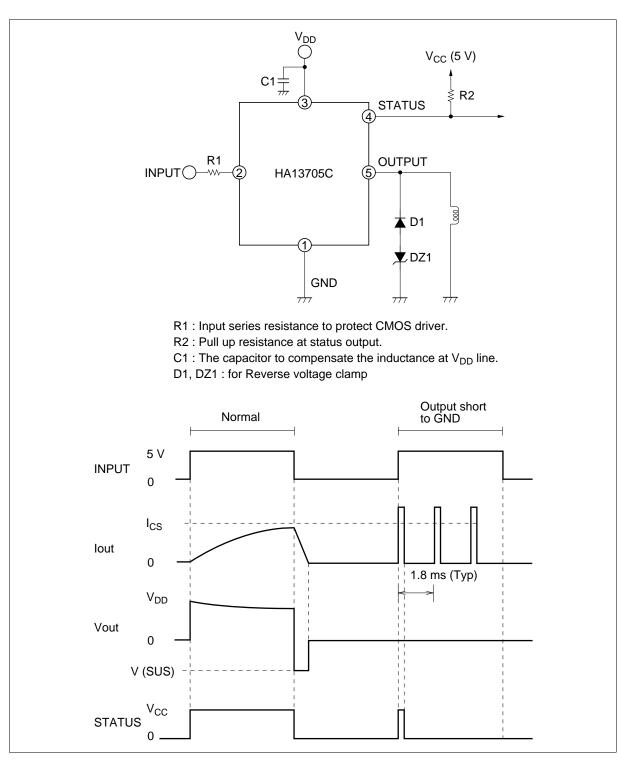


- 4. Internally limited
- 5. Maximum power dissipation (P_{τ} (Max)) can be defined as: P_{τ} (Max) = (Tjopr(Max) – Tambient) / (θ j-c + θ c-a) θ c-a: Thermal resistance between case and air (Depend on heat sink size)

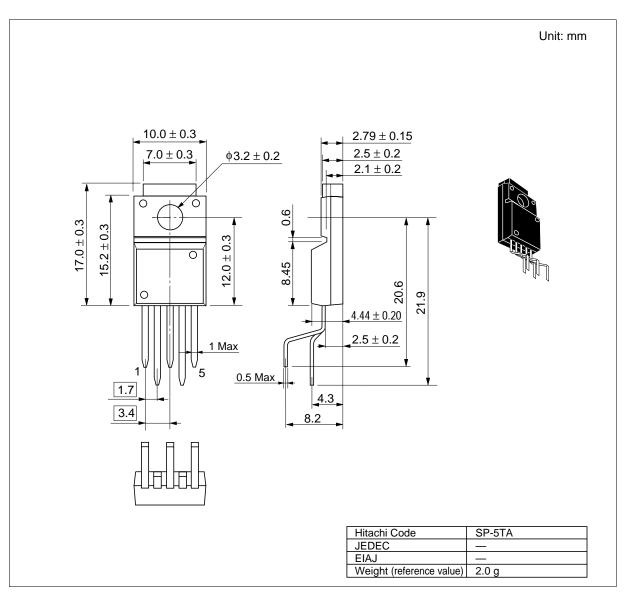
ltem		Symbol	Min	Тур	Max	Unit	Test Conditions	Pin	Note
Output R (C	DN)	$R_{DS(ON)}$	—	0.17	0.36	Ω	I _o = 2 A (@Tj = −40 to 150°C)	5	
Operating s voltage rang		V_{DD}	7	_	25	V		3	
Quiescent current		I _{DD1}	_	_	0.3	mA	$V_{IN} = 0 V$, Vout = 0 V	3	
		I _{DD2}	_	6.0	10.0	mA	$V_{IN} = 5.5 V$, Vout = open	3	
Output leakage current		Ι _{LEAK}	_	_	0.1	mA	$\label{eq:V_DD} \begin{array}{l} V_{\text{DD}} = 25 \ V, \ V_{\text{IN}} = 0 \ V, \\ Vout = 0 \ V \end{array}$	5	
Input threshold voltage		V _{IL}			0.8	V		2	
		V _{IH}	2.0			V		2	
Input current		I _{IL}	-10		60	μA	V _{IN} = 0.8 V	2	
		I _{IH}	50	_	300	μA	V _{IN} = 5.0 V	2	
Propagation delay time		t _{d(ON)}		_	50	μs	I ₀ = 1 A	2, 5	
		t,		_	90	μs	_	5	
		$t_{d(OFF)}$	—	—	50	μs		2, 5	
		Tf	—	—	50	μs		5	
Open det. tl current	hreshold	I _{od}	2	10	100	μs		4, 5	
Current limi level	ter operating	I _{cs}	3.0	4.3	7.5	А		5	
LVI operatir	ng level	L.V.I	_	5	6	V		3	
	Dperating evel	OVSD	26	29	33	V		3	
ŀ	Hysteresis	VHYS	0.15	0.5	1.5	V		3	
Output sust	ain voltage	V _(SUS)		_	-25	V	lout = 20 mA	5	
	Dperating evel	OTSD	150	175		°C		5	1
ŀ	Hysteresis	THYS		15	_	°C		5	1
Status on voltage		V _{SL}		_	0.4	V	I _s = 1 mA	4	
Status loak	age current	I _{S(Leak)}	-10	_	100	μA	V _s = 5.0 V	4	

Notes: 1. Design parameter only (no test)

Solenoid Drive Application and it's Waveform



Package Dimensions



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